

ABSTRACT OF THE DISCLOSURE

Disclosed is a method for packaging a pickup device, which is used for a digital optical instrument, and particularly a method for fabricating an image sensor module connected to a flexible PCB. The method according to the invention includes the steps of forming a printed circuit of a predetermined pattern on an upper surface of a transparent medium, forming a first bump and a second bump on the upper surface of the transparent medium, first bonding the first bump with a pattern of an image chip so as to be electrically connected to each other, secondly bonding the second bump with a circuit of a flexible PCB so as to be electrically connected to each other, and molding a rear surface of the flexible PCB, on which an image chip is mounted, by means of epoxy resin. The method according to the invention provides an effect of reducing weight, thickness, length and size of the module in comparison with the module fabricated under the conventional wire bonding method.

096041847 · 070900